

101350049

SON-1792

RECORDATION FORM COVER SHEET

U.S. DEPARTMENT OF COMMERC

4-11-00 PATEN	TS ONLY Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademarks: Please r	ecord the attached original documents or copy thereof.
 Name of conveying party(ies) Kazuya YONEMOTO Takahisa UENO Ryoji SUZUKI Koichi SHIONO 	2. Name and address of receiving party(ies) Name: SONY CORPORATION Internal Address:
Additional name(s) of conveying party(ies) attached No 3. Nature of conveyance:	Street Address: 7-35 KITASHINAGAWA 6-CHOME SHINAGAWA-KU
□ Assignment □ Merger □ Security Agreement □ Change of Name ○ ○ Change of Name ○ ○ Change of Name ○ March 27, 2000; March 28, 2000; March 28, 2000; March 29, 2000	City: TOKYO, JAPAN Additional name(s) & address(es) attached □ Yes ☒ No
 Application number(s) or patent number(s): If the document is being filed together with a new application, the e 2000; March 28, 2000; March 29, 2000 Additional number(s):	execution date of the application is March 27, 2000; March 28, others attached No
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
Name: Ronald P. Kananen, Esq.	7. Total fee (37 CFR 3.41)\$ 40.00
Internal Address: RADER, FISHMAN & GRAUER Suite 501	☐ Enclosed ☑Authorized to be charged to Deposit Account
	8. Deposit account number:
Street Address: 1233 20th Street, NW City: Washington, D.C. Zip: 20036	18-0013 (Attach duplicate copy of this page if paying by deposit account)

PATENT REEL: 010755 FRAME: 0952

Docket Number: SON-1792

ASSIGNMENT WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SOLID STATE IMAGE SENSING DEVICE AND IMAGE SIGNAL PROCESSING METHOD OF THE SAME for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address: AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention. said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto: And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ______, Filing Date: ______ This assignment executed on the dates indicated below. March 27, 2000 KAZUYA YONEMOTO Execution date of U.S. Patent Application Name of first or sole inventor TOKYO, JAPAN Residence of first or sole inventor Kozinja Imemoto March = 7, 2000

> PATENT REEL: 010755 FRAME: 0953

Date of this assignment

TAKAHISA UENO	Mar 22, 2000
Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of second inventor	
Takahisa Cilina	1/2 27 7000
Signature of second inventor	Mar. 27. 2000 Date of this assignment
RYOJI SUZUKI	march , 28, 2000
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Musii Suruki	march 28 200
Nyoji Suzuki Signature of third inventor	March . 28 . 2000 Date of this assignment
KOICHI SHIONO	march. 24. 200
Name of fourth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of fourth inventor	
	march 29,2000
Signature of fourth inventor	Date of this assignment
organica.	
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment
- `	

PATENT REEL: 010755 FRAME: 0954

RECORDED: 04/11/2000